BALTIC POLYMER SYMPOSIUM 2023



The Baltic Polymer Symposium (BPS) aims to bring together leading academic scientists, researchers and especially young scientists, Ms and Ph.D. students from the Baltics for sharing their research results in the fields of Polymers and Composites (synthesis, processing, recycling).

Scientific Committee

- Prof. Mārtiņš Kalniņš, Dr. Jānis Zicāns, Prof. Remo Merijs-Meri (Latvia)
- Prof. Andres Krumme, Dr. Vitali Sõritski (Estonia)
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 Prof. Arūnas Ramanavičius (Lithuania)



Organized by Institute of Polymer Materials, Faculty of Materials Science and Applied Chemistry, Riga Technical University

INVITATION

It is a great pleasure to inform you that the 21th Baltic Polymer Symposium (BPS 2023) will be held in Latvia, Jelgava, September 20-22, 2023!





You can find registration form here: https://forms.office.com/e/iyr4rMhe60

FEE

The early bird registration fee (till 1 June, 2023) is:

• 280 EUR (200 EUR for students)

The regular registration fee (after 1 June, 2023) is:

• 320 EUR (220 EUR for students)

The fee includes abstracts, proceedings, coffee-breaks, lunches, Welcome Party, Gala Dinner, and the conference tour.

ABSTRACT

Please use the instructions for authors (you can download them here or from the registration form) and send to e-mail: latviabps@gmail.com

or d;

Abstracts should be submitted and presented in English. The text will not be corrected; thus authors are fully responsible for the content of the abstracts.



BPS 2023 will be held in Jelgava, Latvia University of Life Sciences and Technologies (https://www.llu.lv/en)

Accommodation is offered at hotel "Zemgale" (www.skzemgale.lv) and hotel "Jelgava" (www.hoteljelgava.lv)

Accommodation should be booked individually. Please indicate that you are "BPS2023" participant.

IMPORTANT DEADLINES

Abstract submission: 1 July, 2023

Early bird registration: 31 May, 2023

Final registration: 1 July, 2023

The conference fee must be paid by the latest 01.07.2023

We kindly invite you to participate in the Symposium.

